

(12) **United States Patent**  
**Chen et al.**

(10) **Patent No.:** **US 7,372,109 B2**  
(45) **Date of Patent:** **May 13, 2008**

(54) **DIODE AND APPLICATIONS THEREOF**

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(\*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 296 days.

(21) Appl. No.: **11/004,348**

(22) Filed: **Dec. 3, 2004**

(65) **Prior Publication Data**

US 2006/0043489 A1 Mar. 2, 2006

(30) **Foreign Application Priority Data**

Aug. 30, 2004 (TW) ..... 93126050 A

(51) **Int. Cl.**  
**H01L 29/76** (2006.01)

(52) **U.S. Cl.** ..... **257/370**

(58) **Field of Classification Search** ..... 257/500–512,  
257/335, 355–373

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,892,264 A \* 4/1999 Davis et al. .... 257/511  
6,878,605 B2 \* 4/2005 Kim et al. .... 438/424

7,095,092 B2 \* 8/2006 Zhu et al. .... 257/506  
2002/0109190 A1 \* 8/2002 Ker et al. .... 257/355  
2002/0153586 A1 \* 10/2002 Majumdar et al. .... 257/506  
2003/0047750 A1 \* 3/2003 Russ et al. .... 257/173

**OTHER PUBLICATIONS**

“Characteristics of Low-Leakage Deep-Trench Diode for ESD Protection Design in 0.18-μm SiGe BiCMOS Process” Chen et al.; Jul. 2003.

“Low-Leakage Diode String Designs Using Triple-Well Technologies for RF-ESD Applications” Chen et al.; Sep. 2003.

“ESD Protection in a Mixed Voltage Interface and Multi-Rail Disconnected Power Grid Environment in 0.50 and 0.25-μm Channel Length CMOS Technologies” Voldman; 1994.

“Designing On-Chip Power Supply Coupling Diodes for ESD Protection and Noise Immunity” Dabral et al.; 1993.

“Core Clamps for Low Voltage Technologies” Dabral et al.; 1994.

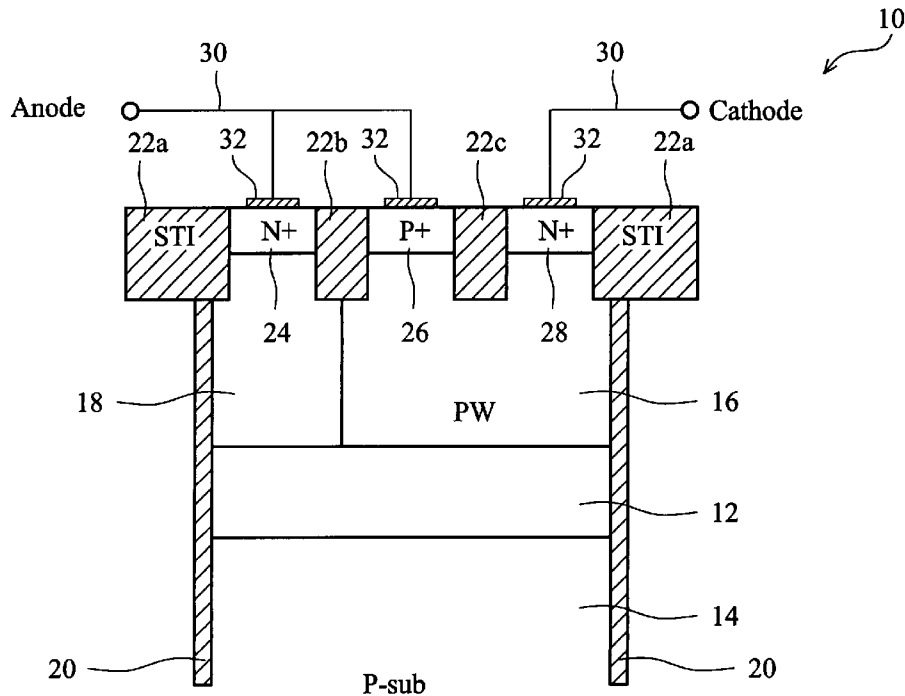
\* cited by examiner

*Primary Examiner*—Nathan W Ha

(57) **ABSTRACT**

A diode with low substrate current leakage and suitable for BiCMOS process technology. A buried layer is formed on a semiconductor substrate. A connection region and well contact the buried layer. Isolation regions are adjacent to two sides of the buried layer, each deeper than the buried layer. The isolation regions and the buried layer isolate the connection zone and the well from the substrate. The first doped region in the well is a first electrode. The well and the connection region are electrically connected, acting as a second electrode.

**24 Claims, 18 Drawing Sheets**



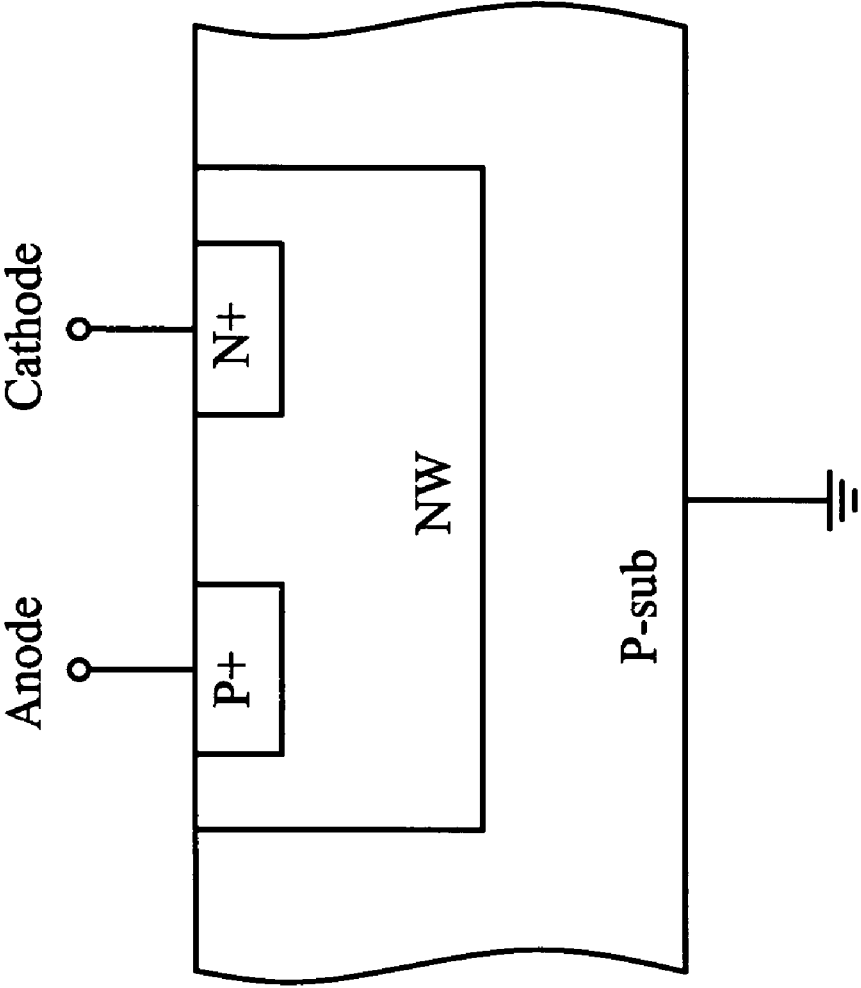


FIG. 1 ( RELATED ART )

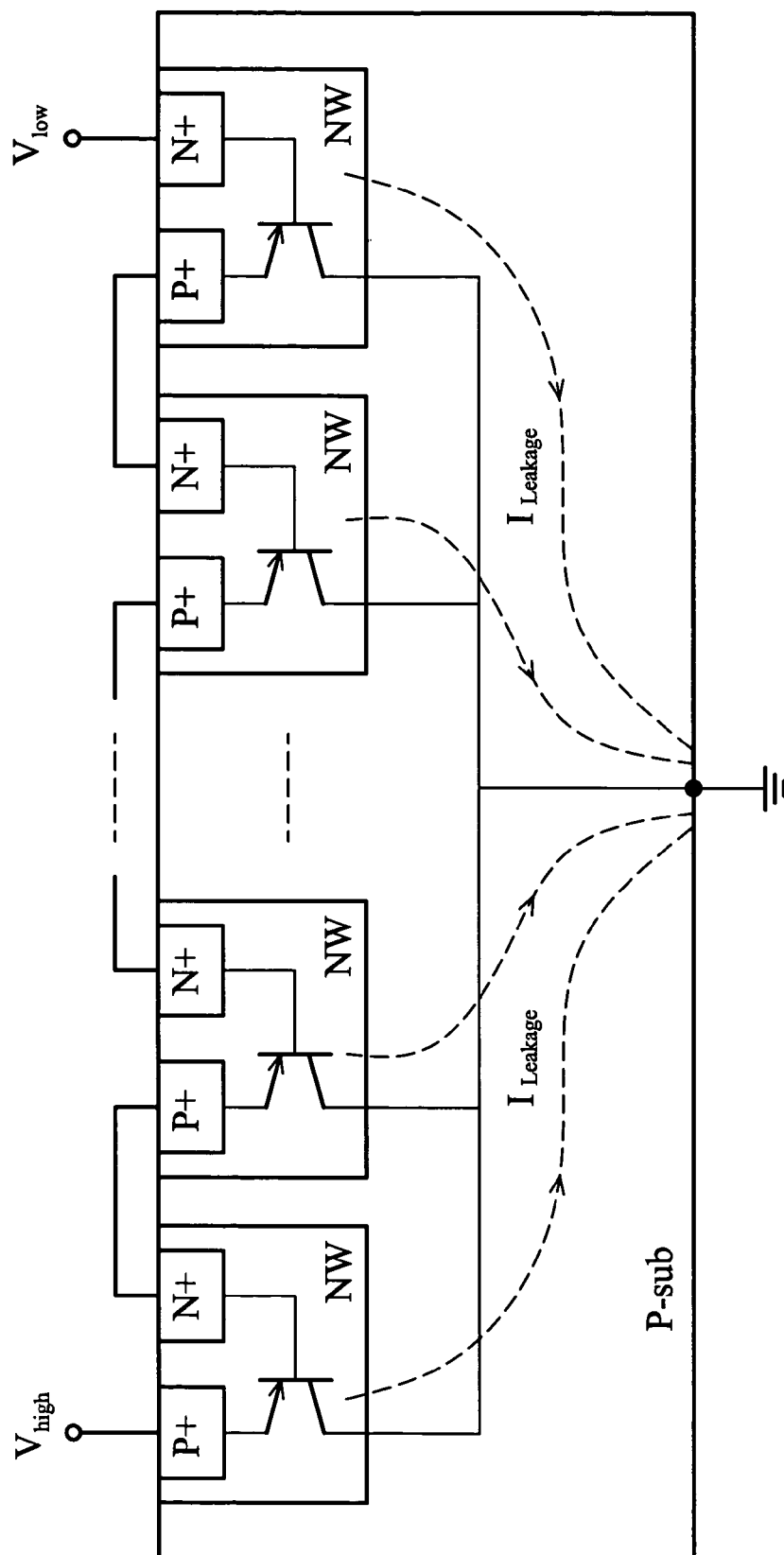


FIG. 2 (RELATED ART)

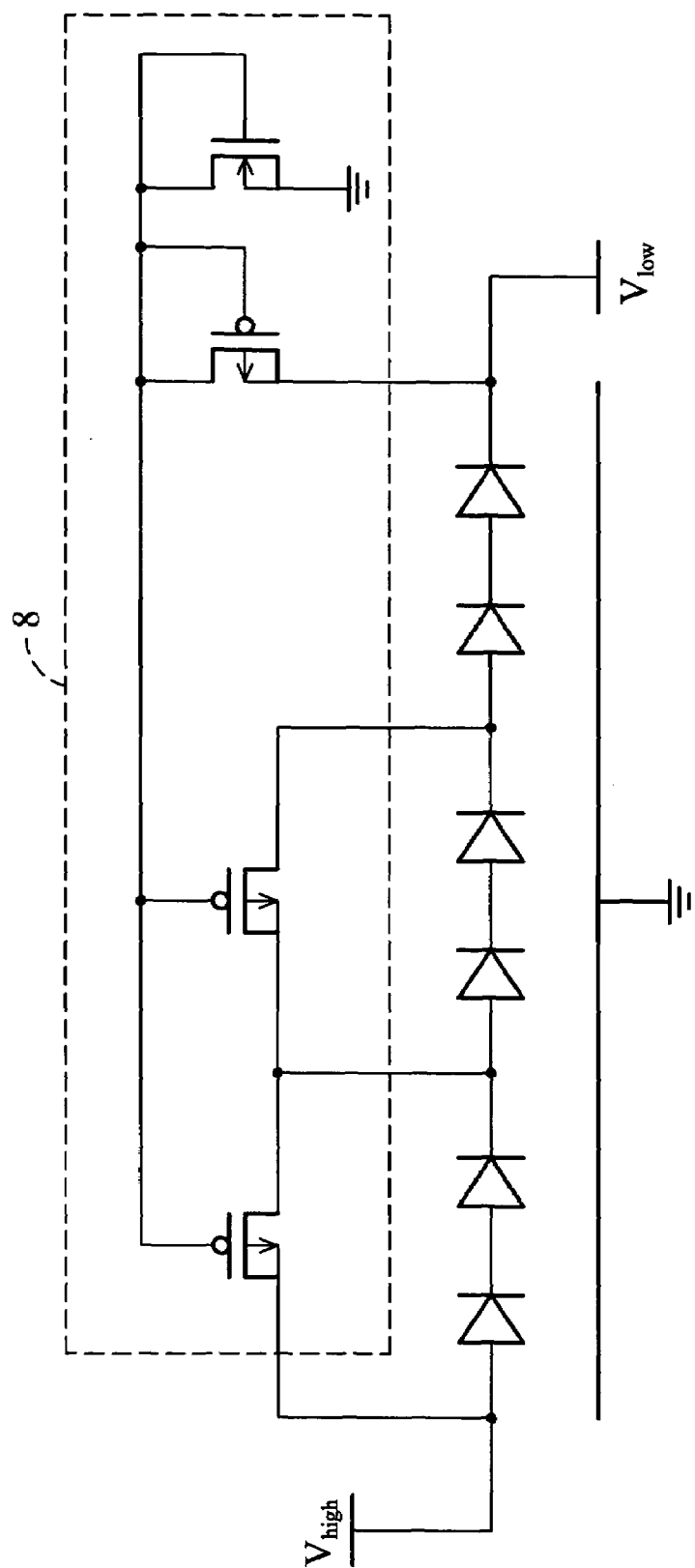


FIG. 3 ( RELATED ART )

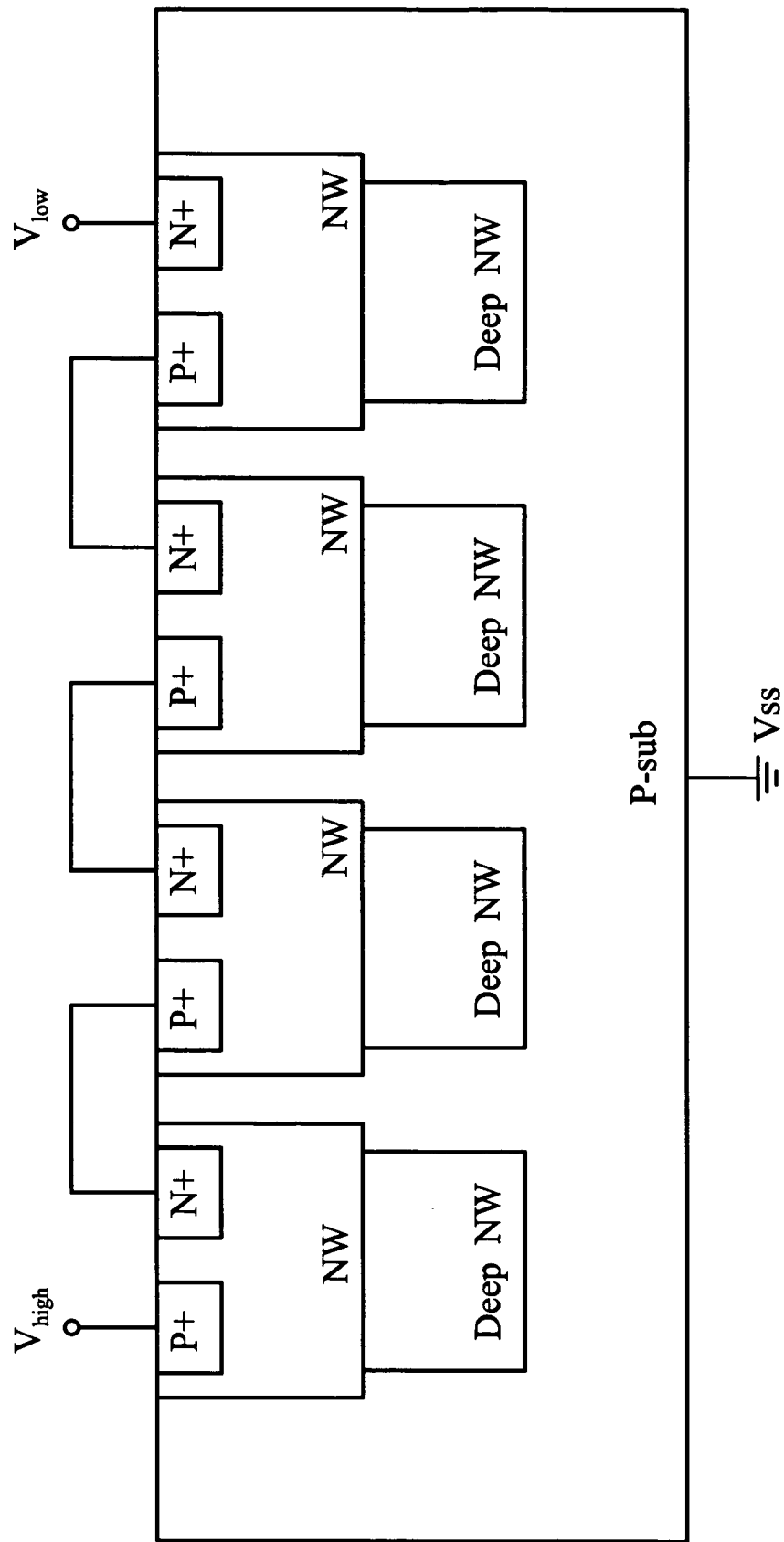


FIG. 4 ( RELATED ART )

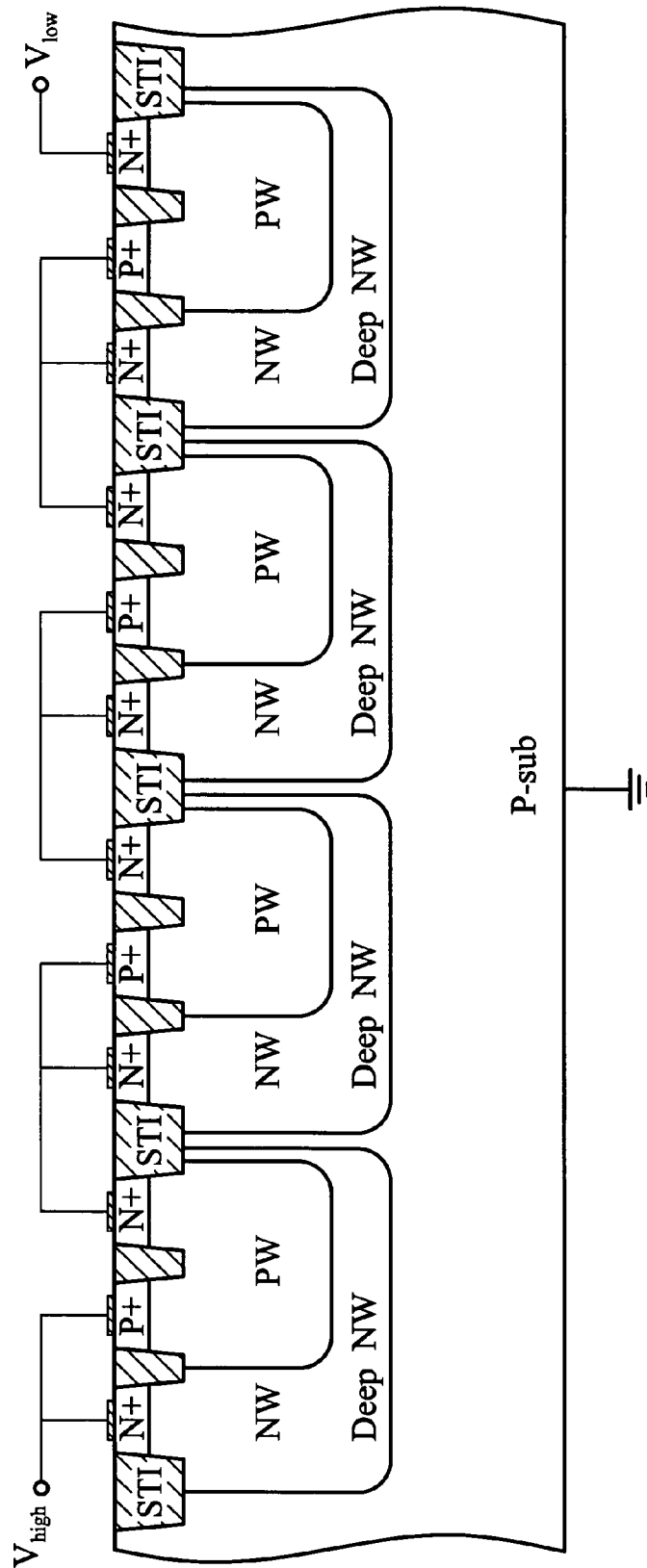


FIG. 5 (RELATED ART)

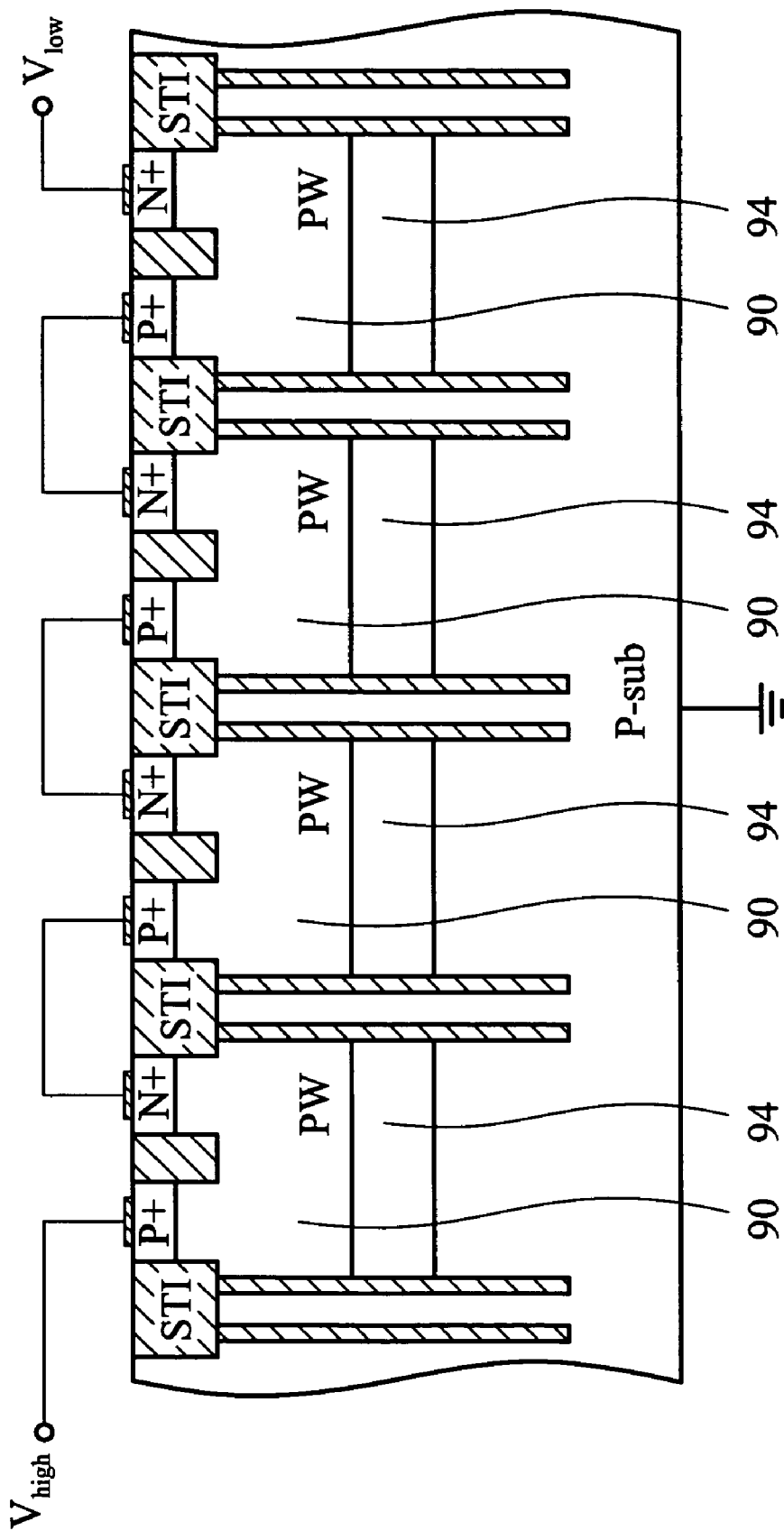


FIG. 6 (RELATED ART)

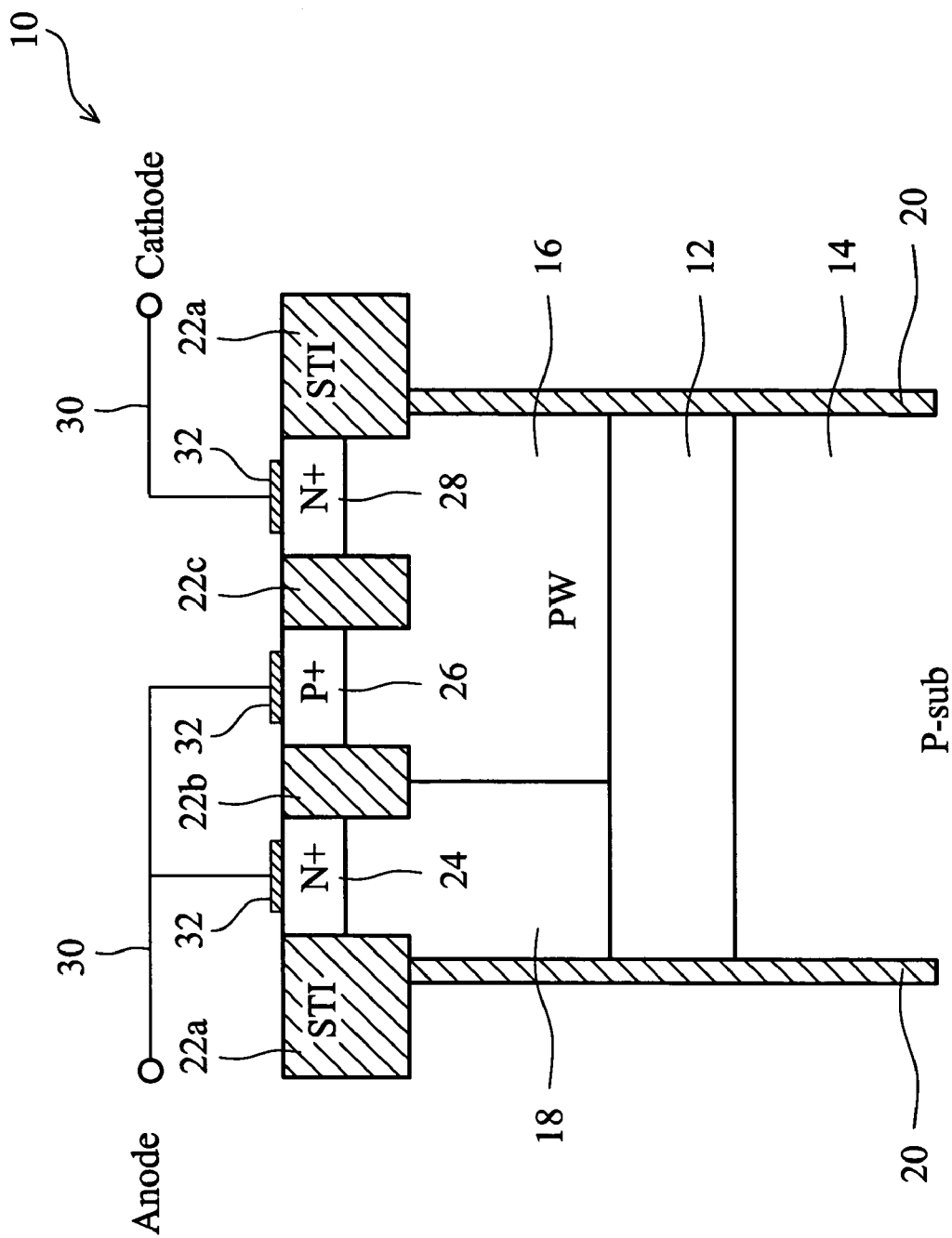


FIG. 7



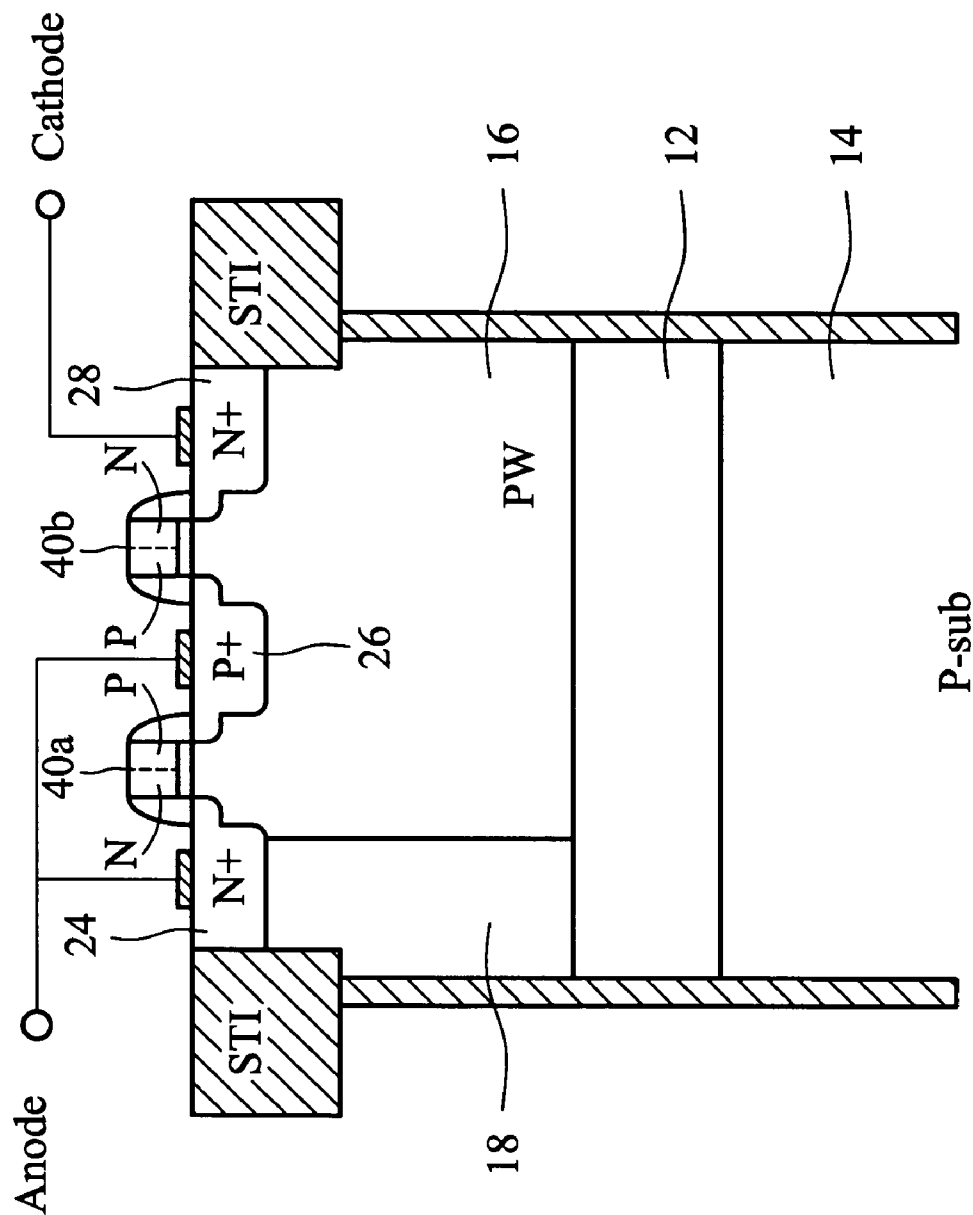


FIG. 8

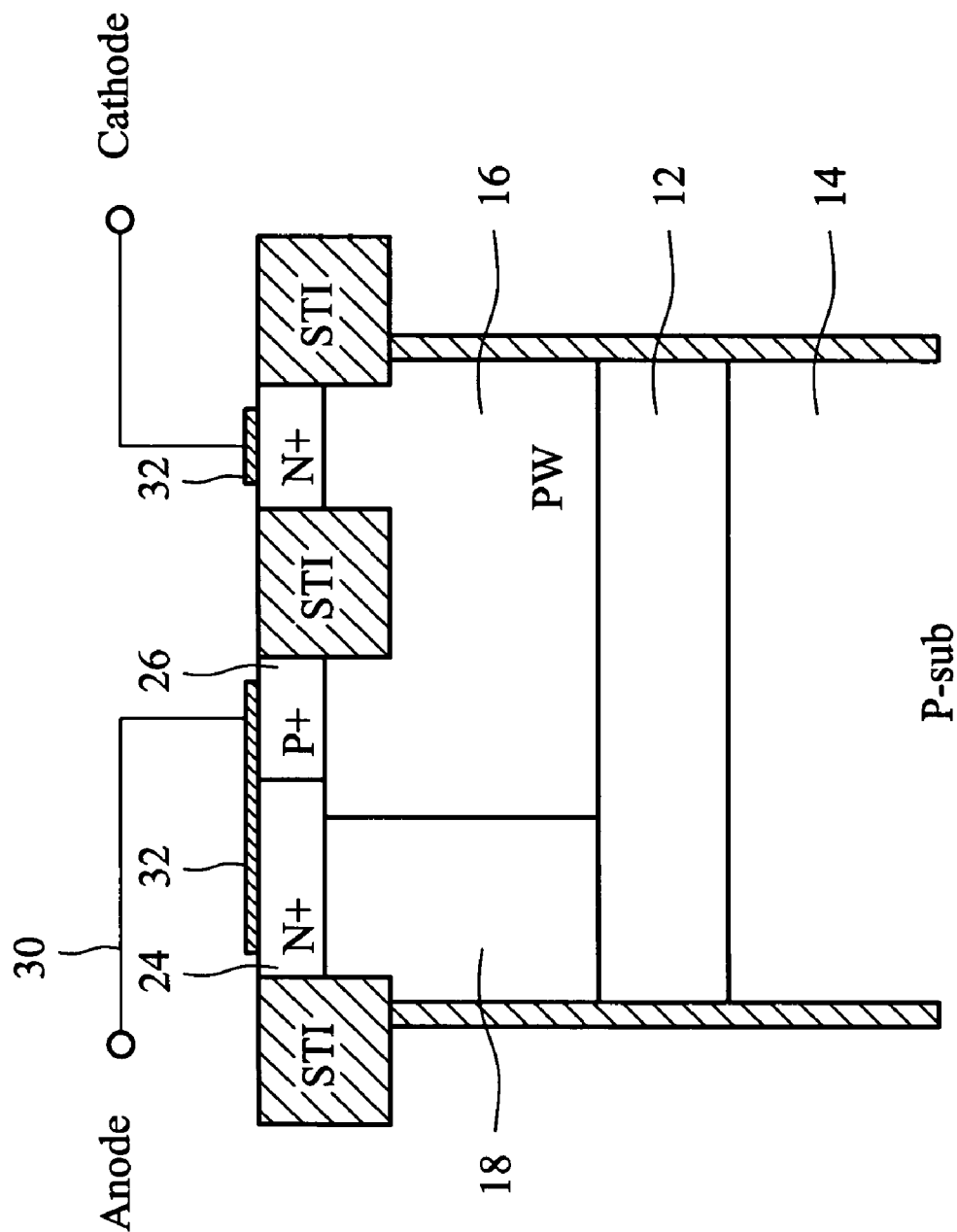


FIG. 9

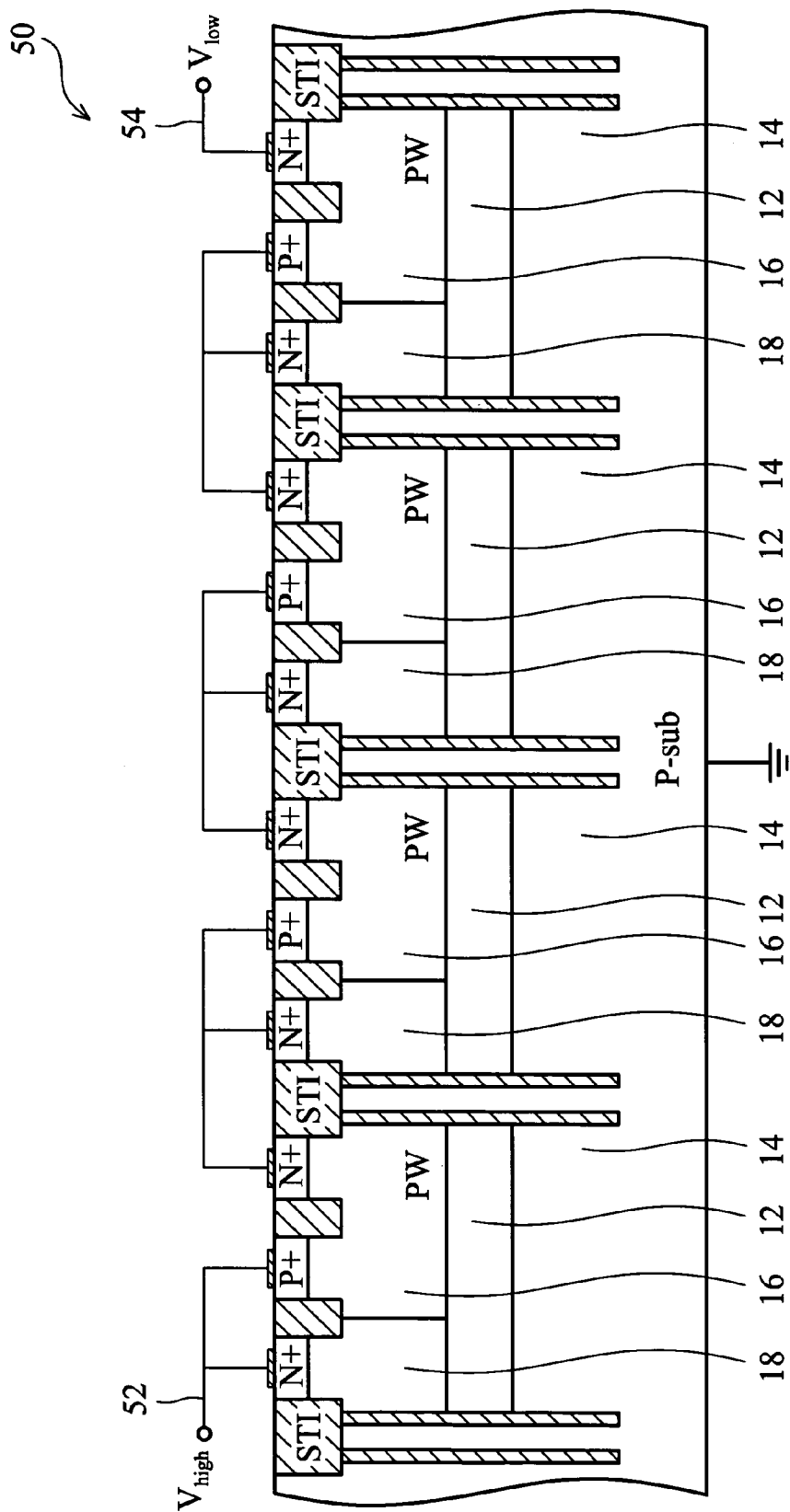


FIG. 10

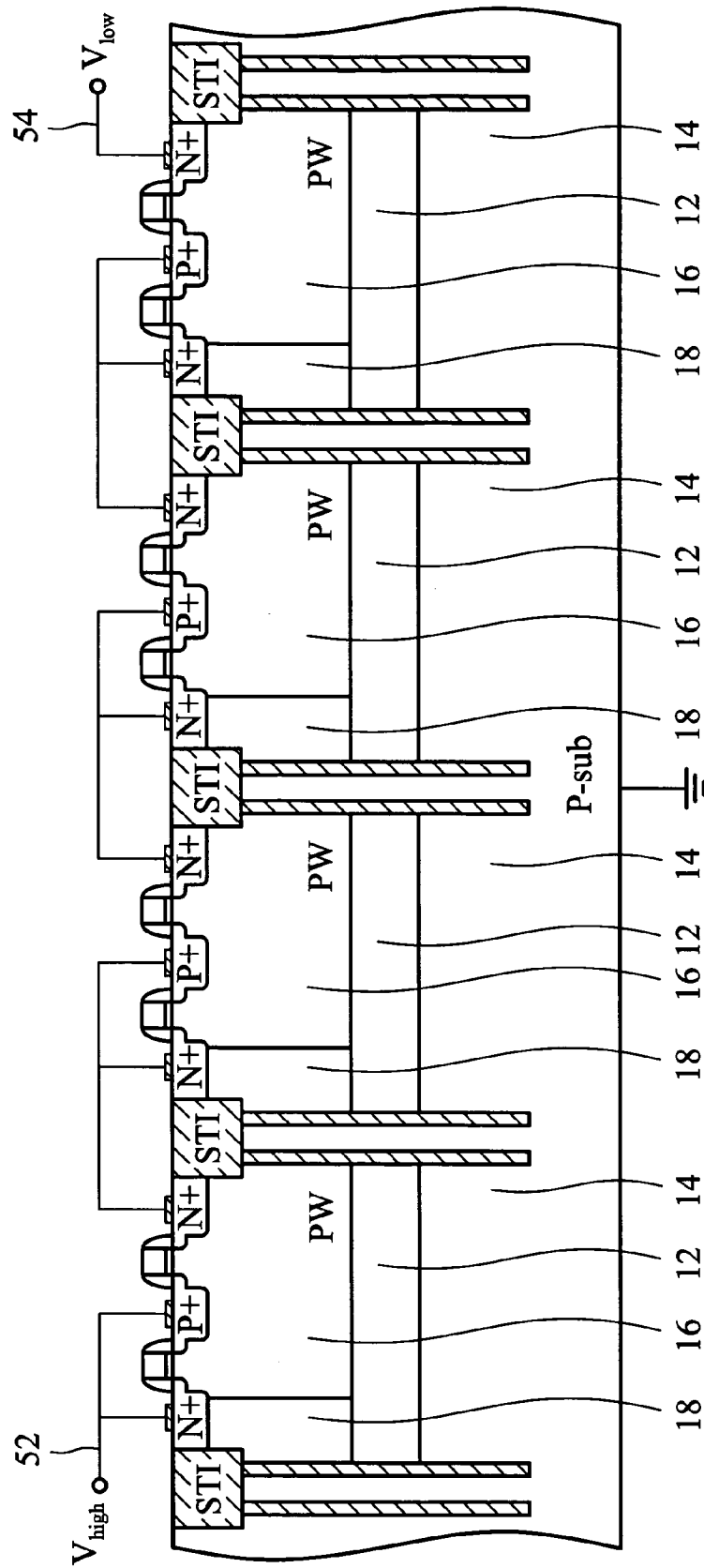


FIG. 11

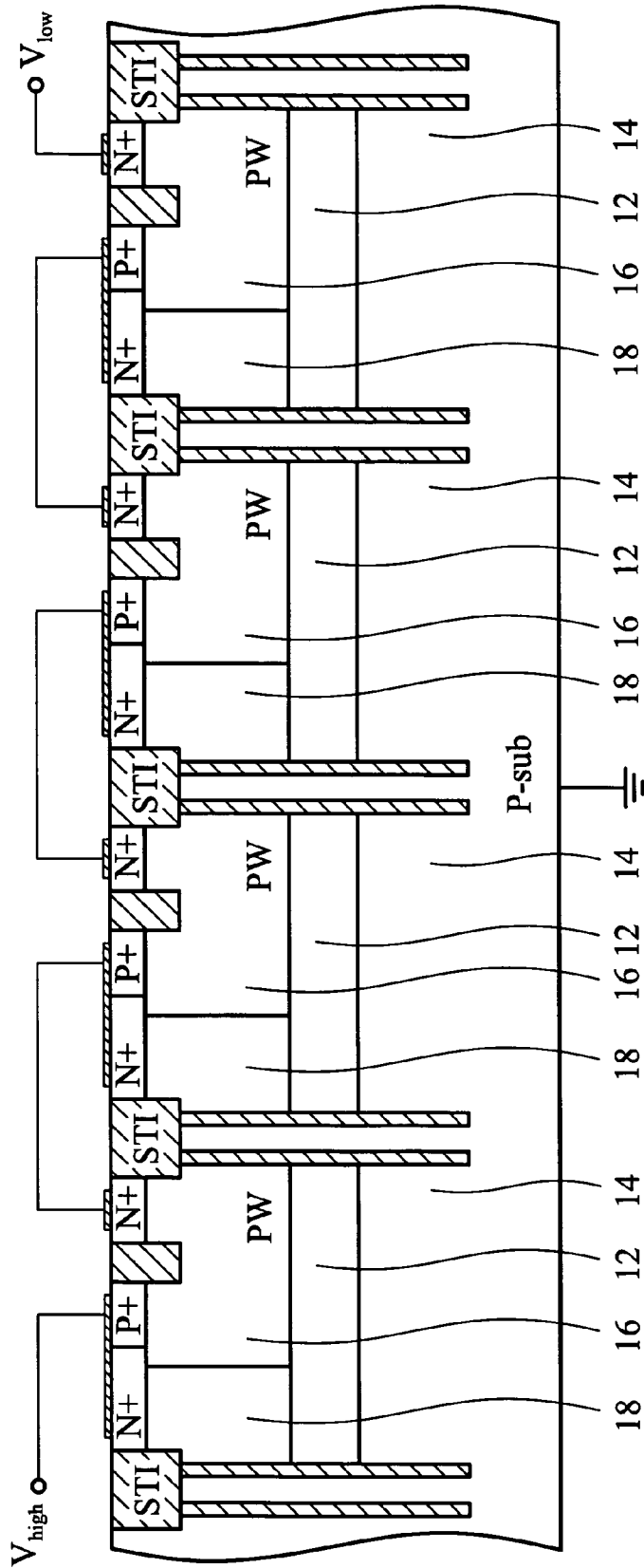


FIG. 12

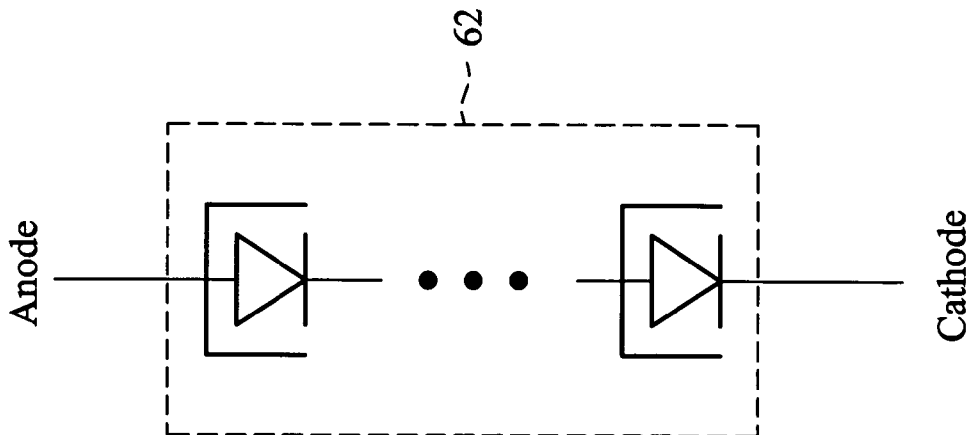


FIG. 13B

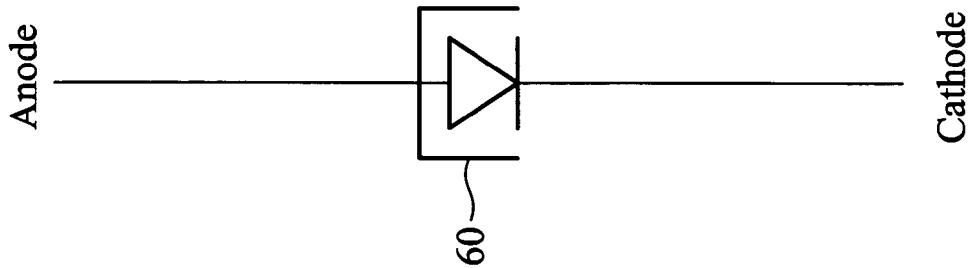


FIG. 13A

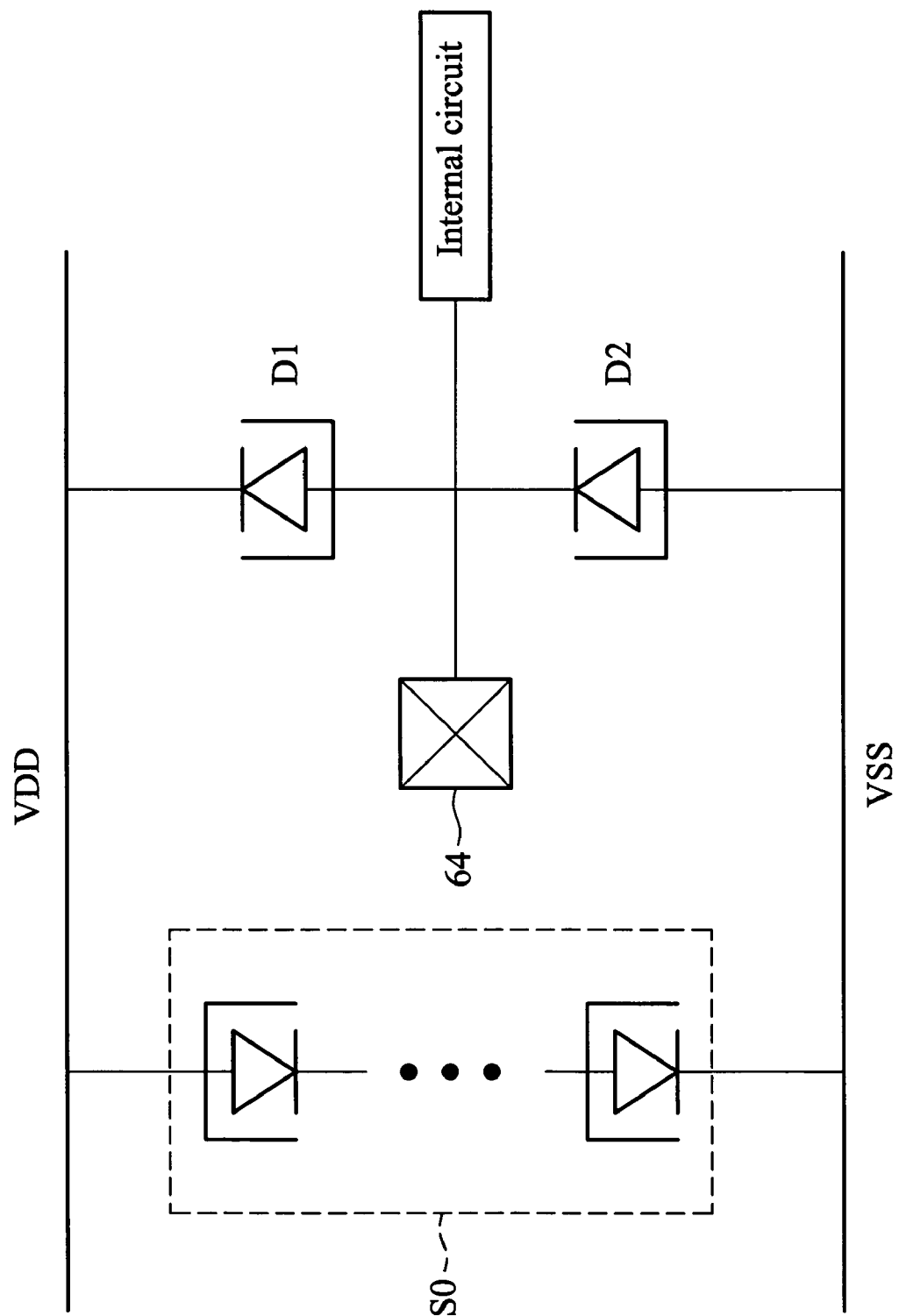


FIG. 14

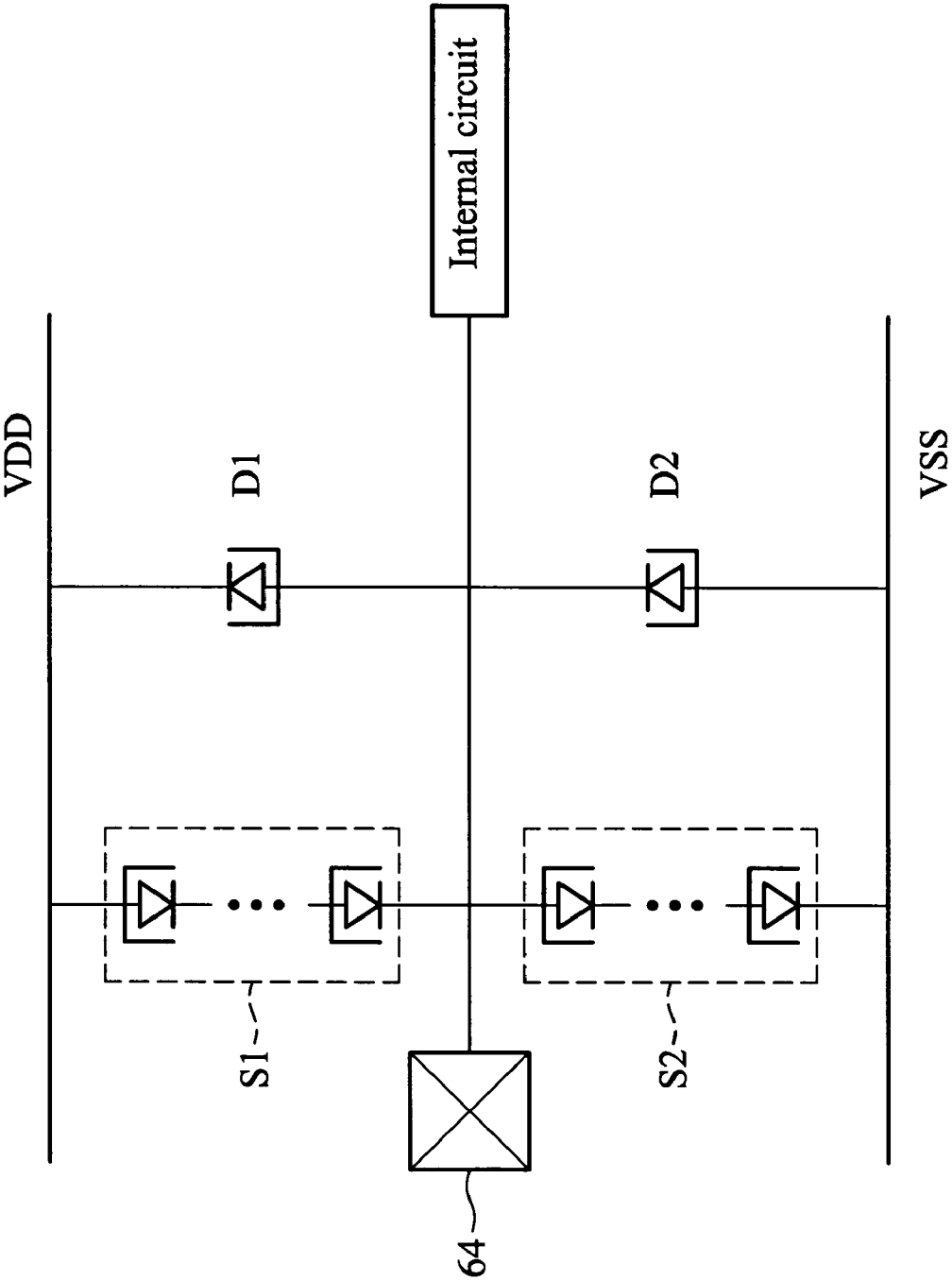


FIG. 15



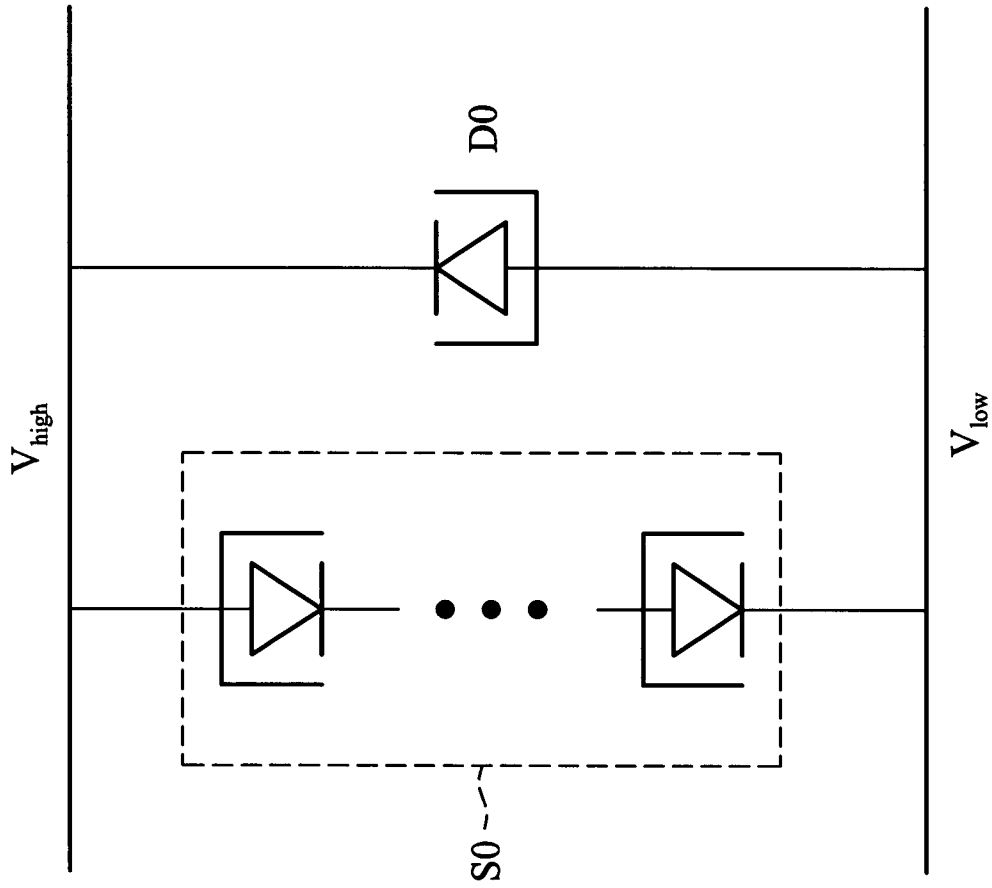


FIG. 16

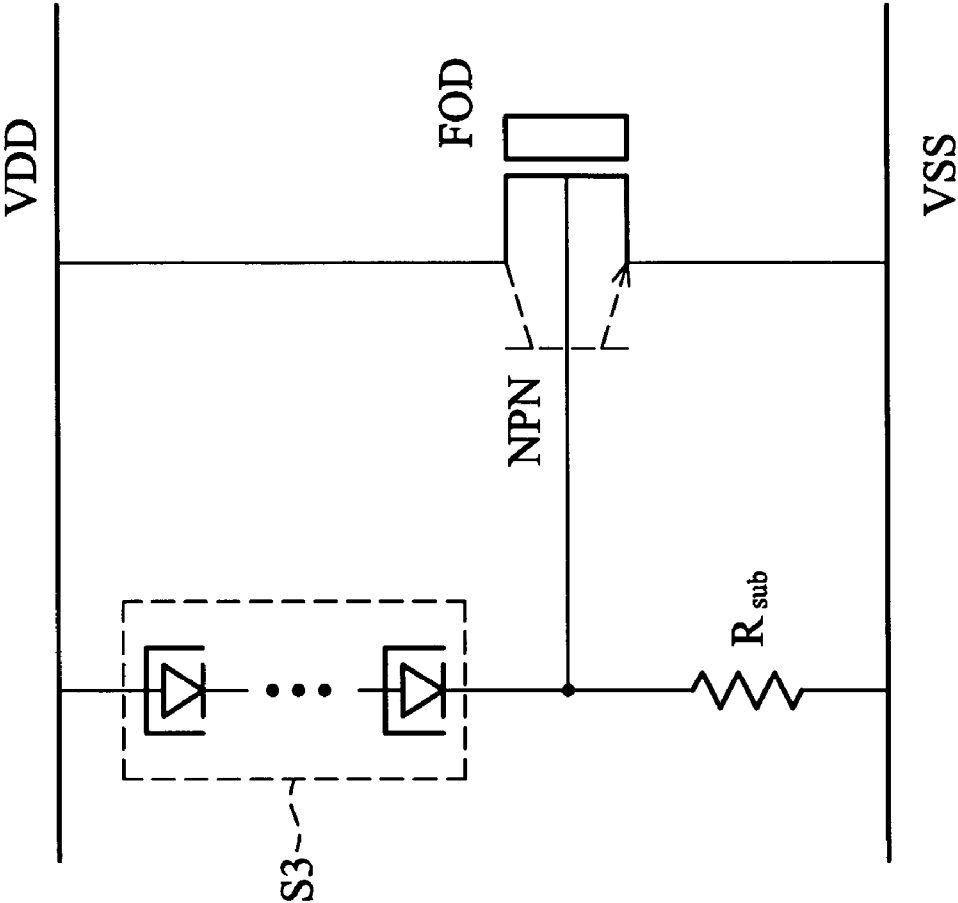


FIG. 17

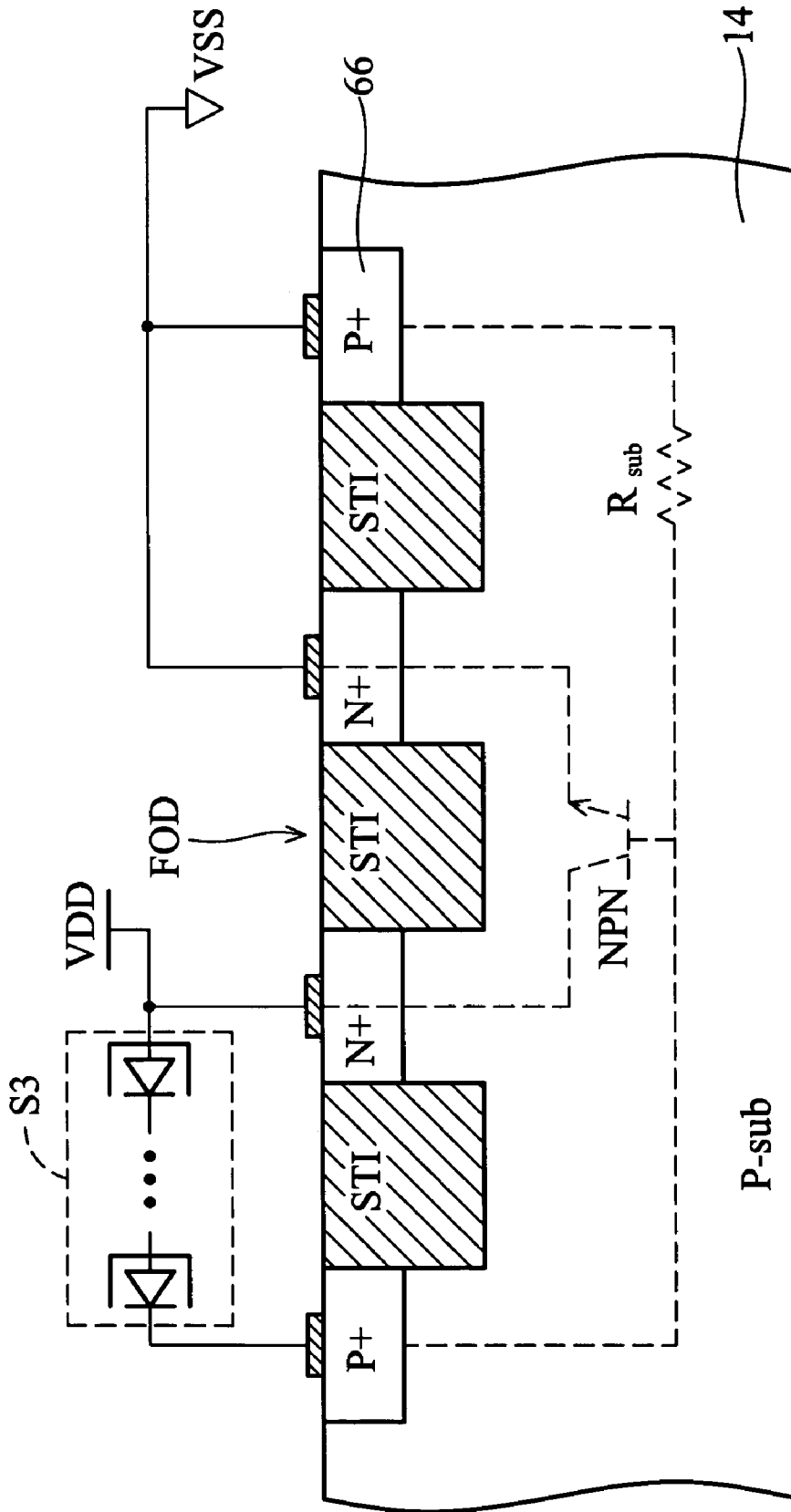


FIG. 18

## DIODE AND APPLICATIONS THEREOF

## BACKGROUND

The present invention relates in general to a diode providing electrostatic discharge (ESD) protection, and in particular to a diode manufactured by bipolar complementary metal oxide semiconductor (BiCMOS) processes.

Among ESD protection devices, a diode has one of the simplest structures. Properly forward biasing a diode during an ESD event requires only a small silicon area for effective protection. FIG. 1 is a cross section of a conventional diode formed with a heavy-doped P-type (P+) region and an N-type well (NW).

FIG. 2 shows a conventional diode string, connected between high voltage ( $V_{high}$ ) and low voltage ( $V_{low}$ ) power lines, serving as an ESD protection device. The conventional diode string consists of several diodes connected in series. As shown in FIG. 2, a parasitic Darlington amplifier is formed in the diode string by the series-connected parasitic PNP bipolar transistors (BJTs), resulting in substrate current leakage forward to the grounded P-type (P) substrate. This substrate current leakage becomes more severe when operating temperature or diode number in the diode string increases.

There are several solutions for substrate current leakage. FIG. 3 shows a conventional circuit schematic suppressing substrate current leakage, in which the bias circuit 8 conducts a small amount of forward current to a lower portion of a diode string. Experimental results from the circuit indicate that, at high temperature, substrate current leakage still occurs at significant magnitude.

Another solution involves modification of the structure of each diode. By lowering the common-base gain of each parasitic BJT, the overall current gain of a Darlington amplifier is decreased, reducing substrate current leakage. Alternatively, eliminating formation of a Darlington amplifier, the substrate current leakage of a diode string may be substantially diminished. FIG. 4 shows a diode string with diodes of an exemplary diode structure. In comparison with the diode of FIG. 1, each diode in FIG. 4 has not only a P+ region and an NW, but also a deep NW under the NW. The common-base current gain of each parasitic BJT is reduced by the enlarged base width thereof. The overall current gain of a Darlington amplifier is accordingly decreased, and the substrate current leakage is reduced.

FIG. 5 shows another diode string in which, for each diode, the P-type well (PW) is completely enclosed by an NW and a deep NW. Through a wire connection, the voltage potentials of the NW and the deep NW are the same as that of the anode of the enclosed diode. In FIG. 5, because the base and emitter of each parasitic PNP BJT are at the same voltage potential and the emitter, the PW, has much lower doped concentration, the common-base current gain of each parasitic PNP BJT is decreased, such that each parasitic PNP BJT is difficult to activate. Furthermore, the Darlington amplifier is not formed, due to the modification of the diode structure, improving substrate current leakage.

The diodes in FIGS. 4 and 5 are suitable for CMOS semiconductor processes providing formation of a deep NW. However, with regard to a diode string with ESD protection for SiGe BiCMOS processes, the diode string in FIG. 6 is generally utilized. In FIG. 6, each diode has a heavy-doped N-type (N+) buried layer 94. Because the emitter, the PW 90, has a much lower doping concentration, the common-base current gain of each parasitic PNP BJT is decreased.

Furthermore, the Darlington amplifier is not formed, due to modification of the diode structure. Both results improve substrate current leakage.

## SUMMARY

Embodiments of the present invention provide a diode with low substrate current leakage. The diode comprises a semiconductor substrate, a buried layer, a well, a connection region, two isolation regions, and a first doped region. The semiconductor substrate is of a first conductivity type. The buried layer is formed on the semiconductor substrate and of a second conductivity type opposite to the first conductivity type. The well is of the first conductivity type, formed on the buried layer. The connection region is of the second conductivity type, formed on the buried layer and contacting the buried layer. The two isolation regions are respectively formed at two sides of the buried layer, each deeper than the buried layer. The isolation regions, together with the buried layer, isolate the well and the connection region from the semiconductor substrate. The first doped region is of the second conductivity type and, on the well, acts as a first electrode of the diode. The connection region and the well are electrically connected to each other, acting as a second electrode of the diode.

The first conductivity type can be P-type and the second conductivity type N-type.

The connection region can be a sinker or another well.

Each isolation region can consist of a single deep trench or one deep trench and a shallow trench.

On the surfaces of the connection region and the well, second and third doped regions can be formed as electrical contacts.

The second and third doped regions can be connected via a wire connection or a silicide layer on the surfaces thereof.

A shallow trench or dummy gate can be formed between each two doped regions for electrical isolation.

The invention also provides an ESD protection circuit with a diode string. The ESD protection circuit can be employed in an input/output (I/O) port or between two power rails.

The voltage potential of a buried layer is the same as the anode of a diode on the buried layer, resulting in a parasitic BJT with a base and emitter of the same voltage potential. This parasitic BJT is difficult to activate during normal operation and has a lower common-base current gain, and, there no Darlington amplifier is formed in a diode string utilizing the diode of the invention.

## BRIEF DESCRIPTION OF THE DRAWINGS

The invention can be more fully understood from the detailed description given hereinbelow and the accompanying drawings, given by way of illustration only and thus not intended to be limitative.

FIG. 1 is a cross section of a conventional diode formed with a heavy-doped P-type region and an N-type well;

FIG. 2 shows a conventional diode string;

FIG. 3 shows a conventional circuit schematic;

FIG. 4 shows a diode string with diodes of an exemplary diode structure;

FIG. 5 shows another diode string with diodes of an exemplary diode structure;

FIG. 6 shows a conventional diode string applicable in SiGe BiCMOS processes;

FIG. 7 shows a diode according to embodiments of the present invention;

FIGS. 8 and 9 show two other diodes according to embodiments of the present invention;

FIG. 10 shows a diode string 50 utilizing the diode in FIG. 7;

FIGS. 11 and 12 show two diode strings utilizing the diodes in FIGS. 8 and 9, respectively;

FIGS. 13A and 13B are two symbols to respectively refer to the diode and the diode string according to the present;

FIG. 14 illustrates an ESD protection circuit for an input/output port according to embodiments of the present invention;

FIG. 15 illustrates another ESD protection circuit for an input/output port according to embodiments of the present invention;

FIG. 16 illustrates a power rail clamping circuit according to embodiments of the present invention;

FIG. 17 illustrates another power rail clamping circuit according to embodiments of the present invention, utilizing substrate triggering; and

FIG. 18 is a cross section of a wafer utilizing the power rail clamping circuit of FIG. 17.

### DESCRIPTION

FIG. 7 shows a diode according to embodiments of the present invention, manufactured by bipolar complementary metal oxide semiconductor (BiCMOS) processes. Diode 10 comprises a P substrate 14, an N+ buried layer 12, a P well (PW) 16, an N+ sinker 18, N+ regions 24 and 28, a P+ region 26, two deep trenches 20 and several shallow trenches 22.

N+ buried layer 12 is disposed on the P substrate 14. PW 16 and N+ sinker 18 are disposed on N+ buried layer 12 and generally formed in an epitaxy silicon layer of a BiCMOS process.

N+ region 24 serves as an electrical contact for N+ sinker 24, and P+ region 26 as an electrical contact for PW 16. On each surface of N+ regions 24 and 28, and P+ region 26, a silicide layer 32 enhances conductivity of each region. Through a wire connection 30, N+ region 24 and P+ region 26 are electrically connected to each other and to other circuits. PW 16, N+ sinker 18 and N+ buried layer 12 thus have the same voltage potential. Wire connections 30 generally consist of contacts, metal lines, vias and the like. Similarly, N+ region 28 can be connected to other circuits through another wire connection 30.

N+ region 28 is formed in PW 16, simultaneously forming a PN junction therein. N+ region 28 thus acts as a cathode of a diode, and PW 16 or its electrical contact, P+ region 26, as an anode of the diode.

In FIG. 7, an isolation region exemplarily comprises a shallow trench 22a and a deep trench 20, both of isolation material, such as silicon dioxide. Each deep trench 20 is deeper than N+ buried layer 12. The cross section in FIG. 7 shows deep trenches 20 respectively contacting two sides of N+ buried layer 12. A top view of the diode in FIG. 7, however, may show that the two deep trenches 20 are in the same isolation zone enclosing the entire N+ buried layer 12.

These two isolation regions, each comprising a deep trench 20 and a shallow trench 22a, together with N+ buried layer 12, electrically isolate PW 16 from P substrate 14. Shallow trench 22c isolates P+ region 26 from N+ region 28, and shallow trench 22b isolates P+ region 26 from N+ region 24.

In related art FIG. 6, N+ buried layer 94 is not connected to PW 90, such that its potential should be lower than that of PW 90. This voltage difference, about that to turn on a PN junction, eases to turn on the parasitic PNP BJT, resulting in

significant substrate current leakage. Nonetheless, in FIG. 7, since PW 16 and N+ buried layer 12 have the same voltage potential, no voltage difference is induced between the emitter and the base of the parasitic PNP BJT, consisting of PW 16, N+ buried layer 12 and P substrate 14. This parasitic PNP BJT is difficult to activate, in addition to much smaller the common-base current gain, causing little substrate current leakage.

The most significant differences between an N+ buried layer of a BiCMOS process and a deep NW of a CMOS process are the functions provided. Generally, in a CMOS circuit, a deep NW provides isolation of a PW and a P substrate. In a BiCMOS circuit, in addition to isolation between a PW and a P substrate, an N+ buried layer usually acts a sub-collector, connecting the collector of a BJT. Accordingly, an N+ buried layer requires low resistance and is heavily doped to reduce sheet resistance. A deep NW, in order to provide adequate isolation, is generally lightly doped to enlarge the junction breakdown voltage between itself and a P substrate. As an example, for a 0.18 um BiCMOS process, the dosage concentration of an N+ buried layer is about  $10^{15}/\text{cm}^2 \sim 10^{17}/\text{cm}^2$ ; and for a comparable 0.18 um CMOS process, the dosage concentration of an deep NW is about  $10^{13}/\text{cm}^2 \sim 10^{15}/\text{cm}^2$ .

N+ sinker 18 in FIG. 7 can be replaced by a NW with lighter dosage concentration, capable to connect N+ buried layer 12 and PW to the same voltage potential.

FIG. 8 shows another diode structure according to embodiments of the present invention. Unlike the two shallow trenches 22c and 22b shown in FIG. 7, which isolate N+ region 24, P+ region 26 and N+ region 28, in FIG. 8, they are respectively replaced by two dummy gates 40a and 40b. Each dummy gate has a polysilicon gate. During ion implantation to form N+ regions 24 and 28, a portion of the polysilicon gate adjacent to a N+ region is simultaneously doped into N-type doped polysilicon. During ion implantation to form P+ region 26, a portion of the polysilicon gate adjacent to a P+ region is simultaneously doped into P-type doped polysilicon, as shown in FIG. 8.

The shallow trench or dummy gate between P+ region 26 and N+ region 24 can be omitted to conserve space. FIG. 9 shows another diode according to embodiments of the present invention. Unlike FIG. 7, FIG. 9 lacks shallow trench 22c. As shown in FIG. 9, a silicide layer 32 on surfaces of P+ region 26 and N+ region 24 shorts them. Hence, the wire connection 30 for P+ region 26 and N+ region 24 requires only a contact hole for necessary connection to the anode of a diode.

FIG. 10 shows a diode string 50 utilizing the diode in FIG. 7. In FIG. 10, the diode string 50 consists of 4 diodes forward connected in series, wherein an anode of a diode is connected to a cathode of another diode, whose anode is connected to a cathode of another diode, such that, each diode has the same polarity. The diode string 50 thus acts as a compound diode having an activation voltage equal to the sum of all the activation voltages of the diodes therein, a major anode at the anode of the first diode in the diode string 50, and a major cathode at the cathode of the last diode in the diode string 50. While in FIG. 10, the number of the diodes is 4. The disclosure is not limited thereto. In application, the number of diodes forward connected in series is determined by, and proportional to, activation voltage required for the diode string.

Acting as an ESD protection device, the major anode and cathode of the diode string 50 are generally coupled to metal lines 52 and 54, respectively, with voltage potential of the metal line 52 normally exceeding that of the metal line 54.

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For example, when the metal line 52 is a high voltage power rail, the metal line 54 can be a low voltage power rail or an input/output (I/O) pad of an input/output port. When the metal line 54 is a low voltage power rail, the metal line 52 can be a high voltage power rail or an input/output pad of an input/output port.

FIGS. 11 and 12 show diode strings utilizing the diode structures in FIGS. 8 and 9, respectively, and are self-explanatory to a person skilled in the art.

There is no requirement that all the diodes in a diode string have the same diode structure. Each diode in a diode string can have a unique diode structure. For example, a diode of FIG. 7 can be forward connected in series with a diode of FIG. 9 to form a diode string.

FIGS. 13A and 13B are two symbols to respectively refer to the diode and the diode string according to the present invention. Hereinafter, symbol 60 in FIG. 13A represents a diode according to the present invention and could be anyone of FIGS. 7, 8, and 9. Symbol 62 in FIG. 13B represents a diode string according to the present invention and has at least two diodes forward connected in series.

FIG. 14 illustrates an ESD protection circuit for an input/output port according to embodiments of the present invention. A diode D1 is connected between a power rail VDD and an I/O pad, and a diode D2 connected between an I/O pad 64 and a VSS power rail. During normal operation, both the diodes D1 and D2 are reverse biased. A diode string S0 is connected between the VDD and VSS power rails, with diodes therein forward biased during normal operation. When an ESD pulse relatively positive to the VSS power rail occurs at the I/O pad 64, ESD charges can be released through the I/O pad 64, the diode D1, the VDD power rail and the diode string S0, and to the VSS power rail, thereby protecting internal circuits from ESD damage. Since diodes D1 and D2 are forward biased to conduct ESD current, they can be small in size. This ESD protection circuit is especially suitable for radio frequency (RF) integrated circuits (ICs). As shown in FIG. 14, only two small diodes D1 and D2 are additionally connected to the I/O pad 64, adding little capacitance loading and significant diminishing influence of the high frequency response on the I/O port.

FIG. 15 illustrates another ESD protection circuit for an input/output port according to embodiments of the present invention. A diode D1 and a diode string S1 are connected in parallel between the VDD power rail and an I/O pad 64 while a diode D2 and a diode string S2 are connected in parallel between the VSS power rail and the I/O pad 64. During normal operation, both diodes D1 and D2 are reverse biased, both diode strings S1 and S2 are forward biased, and all diodes D1 and D2 and diode strings S1 and S2 are open circuits. When an ESD pulse relatively positive to the VSS power rail occurs at the I/O pad 64, ESD charges can be released through the forward biased diode string S2 and to the VSS power rail, thereby protecting internal circuits from ESD damage.

FIG. 16 illustrates a power rail clamping circuit according to the present invention. A diode D0 and a diode string S0 are connected in parallel between a  $V_{high}$  power rail and a  $V_{low}$  power rail. During normal operation, the diode D0 is reverse biased and the diode string S0 forward biased. When an ESD pulse relatively positive/negative to the  $V_{low}$  power rail occurs at the  $V_{high}$  power rail, ESD charges can be released through the forward biased diode string S0/diode D0 and to the VSS power rail, thereby protecting internal circuits from ESD damage.

FIG. 17 illustrates another power rail clamping circuit according to embodiments of the present invention, utilizing

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substrate triggering. FIG. 18 is a cross section of a wafer utilizing the power rail clamping circuit of FIG. 17. In FIG. 17, the primary discharge element is a field oxide MOS transistor FOD connected between VDD and VSS power rails. A diode string S3 and a resistor  $R_{sub}$  are connected in series between the two power rails. The connection node between the diode string S3 and the resistor  $R_{sub}$  is also connected to the base of a parasitic NPN BJT under FOD. In FIG. 18, the resistor  $R_{sub}$  is a spread resistor of the substrate 14 disposed between the base of the NPN BJT and a P+ region 66, a contact of the P substrate 14.

During normal operation, activation voltage of the diode string S3 exceeds the voltage difference between the VDD and VSS power rails, and, as a result, the diode string S3 and the PNP BJT under FOD remain open. During an ESD event, activation of the diode string S3 conducts small ESD current through the resistor  $R_{sub}$ , and when voltage drop across the resistor  $R_{sub}$  is sufficient, the NPN BJT is activated, conducting large ESD current from the VDD power rail, through the parasitic NPN BJT, and to the VSS power rail.

While the invention has been described by way of example and in terms of the preferred embodiments, it is to be understood that the invention is not limited thereto. To the contrary, it is intended to cover various modifications and similar arrangements (as would be apparent to those skilled in the art). Therefore, the scope of the appended claims should be accorded the broadest interpretation so as to encompass all such modifications and similar arrangements.

What is claimed is:

1. An apparatus, comprising:

- a semiconductor substrate of a first conductivity type;
  - a buried layer of a second conductivity type formed in the semiconductor substrate;
  - a well of the first conductivity type formed adjacent the buried layer;
  - a connection region of the second conductivity type formed in the substrate and contacting the buried layer;
  - two isolation regions, respectively formed in the substrate on two sides of the buried layer, at least one of said isolation regions extending further into the substrate than the buried layer, wherein the isolation regions together with the buried layer isolate the well and the connection region from the semiconductor substrate;
  - a first doped region of the second conductivity type formed in the well and adapted to provide a first electrode of a diode; and
  - an anode/cathode interface between the well and the first doped region, the anode/cathode interface extending into the substrate a distance less than the depth of the top of the isolation regions,
- wherein the connection region and the well are adapted to be electrically connected and to provide a second electrode of the diode.

2. The apparatus of claim 1, wherein at least one of said isolation regions comprise:

- a deep trench; and
- a shallow trench formed on the deep trench.

3. The apparatus of claim 1, further comprising a second doped region of the first conductivity type in the well, isolated from the first doped region, and adapted to provide an electrical contact of the well.

4. The apparatus of claim 3, further comprising a shallow trench between the first and the second doped regions.

5. The apparatus of claim 3, further comprising a third doped region of the second conductivity type formed on the connection region, isolated from the second doped region,

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and adapted to provide an electrical contact of the connection region and the buried layer.

6. The apparatus of claim 5, further comprising a shallow trench formed between the third and second doped regions.

7. The apparatus of claim 1, wherein the connection region comprises a sinker.

8. A system, comprising:

at least one diode, comprising:

a semiconductor substrate of a first conductivity type;

a buried layer formed in the semiconductor substrate of a second conductivity type;

a well of the first conductivity type formed on the buried layer;

a connection region of the second conductivity type formed on and contacting the buried layer;

two isolation regions, formed respectively on two sides of the buried layer, at least one of said isolation regions extending further into the substrate than the buried layer, wherein the isolation regions together with the buried layer isolate the well and the connection region from the semiconductor substrate;

a first doped region of the second conductivity type formed on the well and adapted to provide a first electrode of the diode; and

an anode/cathode interface between the well and the first doped region, the anode/cathode interface extending into the substrate a distance less than the depth of the top of the isolation regions,

wherein the connection region and the well are adapted to be electrically connected and to provide a second electrode of the diode;

a first wire connection, electrically coupled to the first electrode; and

a second wire connection, electrically coupled to the second electrode;

wherein one of the first or second wire connection comprises a first power rail.

9. The system of claim 8, wherein the other wire connection comprises a second power rail.

10. The system of claim 8, wherein the other wire connection is connected to an input/output pad.

11. The system of claim 8, further comprising a plurality of additional diodes forward connected in series to form a diode string including first and second major electrodes, wherein the first and second wire connections are respectively connected to the first and second major electrodes, and, wherein during normal operation, one or more diodes are adapted to be forward biased.

12. The system of claim 11, further comprising a second diode coupled between the first and second wire connections and adapted to be reverse biased during normal operation.

13. The system of claim 11, further comprising:

a primary discharge element coupled between the first and second wire connections and having a trigger node; and

a resistor connected with the diode string through a connection node;

wherein the resistor and the diode string are connected in series between the first and second wire connections, and wherein the connection node is connected to the trigger node.

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14. The system of claim 11, wherein the primary discharge element comprises a field oxide MOS transistor, the trigger node comprises a base of a parasitic BJT in the field oxide MOS transistor, and the resistor comprises a spread resistor of the semiconductor substrate connected between the base and a contact of the semiconductor substrate.

15. An apparatus, comprising:

a semiconductor substrate of a first conductivity type, the substrate having formed therein:

a well of a first conductivity type;

a connection region of a second conductivity type adjacent to the well;

a buried layer of the second conductivity type disposed between the substrate and the well, and between the substrate and the connection region;

a first isolation region adjacent to the well; and

a second isolation region adjacent to the connection region

a first doped region of the second conductivity type formed on the well and adapted to provide a first electrode of the diode; and

an anode/cathode interface between the well and the first doped region, the anode/cathode interface extending into the substrate a distance less than the depth of the top of the isolation regions,

wherein the buried layer and the isolation regions electrically isolate the well and the connection region from the substrate.

16. The apparatus of claim 15, wherein at least one of the isolation regions comprises a deep trench.

17. The apparatus of claim 16, wherein the deep trench extends further into the substrate than the buried layer.

18. The apparatus of claim 15, wherein the well and the connection region are adapted to provide a second electrode of the diode.

19. The apparatus of claim 15, further comprising:

a second doped region of the first conductivity type formed on the well and adapted to act as an electrical contact of the well, wherein the second doped region is electrically isolated from the first doped region.

20. The apparatus of claim 19, wherein a shallow trench electrically isolates the second doped region from the first doped region.

21. The apparatus of claim 15, further comprising:

a third doped region of the second conductivity type formed in the connection region and adapted to provide an electrical contact of the connection region, wherein the third doped region is electrically isolated from the second doped region.

22. The apparatus of claim 21, wherein a shallow trench electrically isolates the third doped region from the second doped region.

23. The apparatus of claim 16, wherein the first conductivity type comprises p-type conductivity, and wherein the second conductivity type comprises n-type conductivity.

24. The apparatus of claim 16, wherein the connection region comprises a sinker.

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